

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



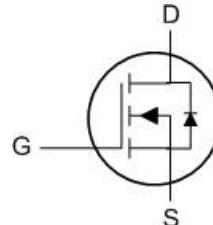
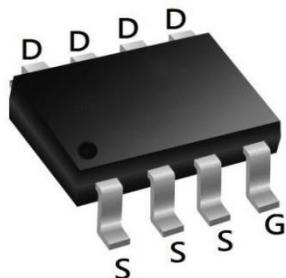
BVDSS	RDS(ON)	ID
20V	13mΩ	10A

Description

The XXW10N02 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XXW10N02 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Rating ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current $T_A = 25^\circ\text{C}$	I_D	10	A
Pulsed Drain Current ¹	I_{DM}	28	A
Power Dissipation $T_A = 25^\circ\text{C}$	P_D	2.25	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$

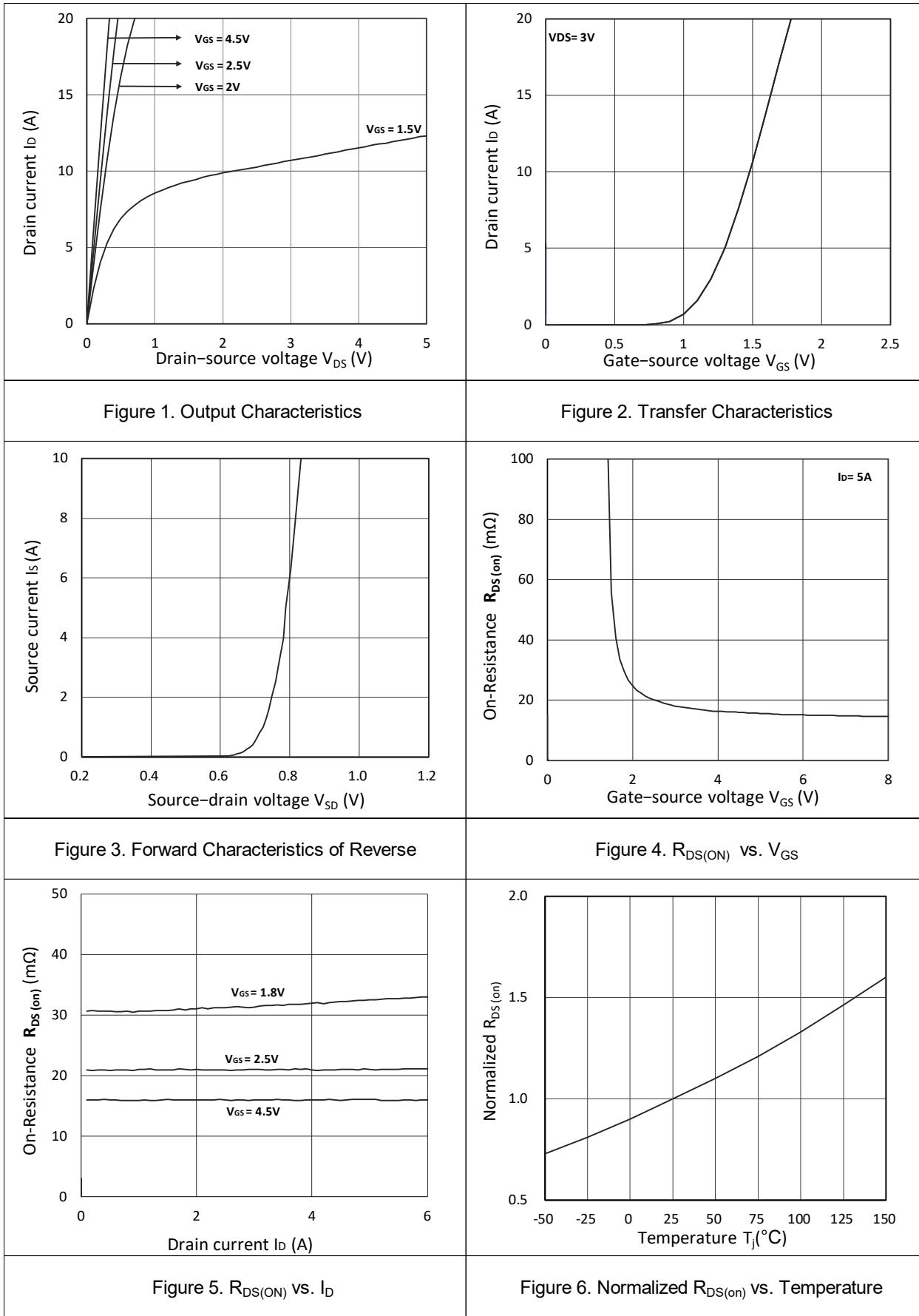
Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V _{GS} = 0V, I _D = 250μA	20	-	-	V
Gate Leakage Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V	-	-	±100	nA
Drain Cut-off Current	I _{DS}	V _{DS} = 20V, V _{GS} = 0V	-	-	1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = 250μA	0.45	0.7	1	V
Drain-Source On-State Resistance ³	R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	13	20	mΩ
		V _{GS} = 2.5V, I _D = 4.7A	-	18	30	
		V _{GS} = 1.8V, I _D = 4.3A	-	28	57	
Dynamic Characteristics⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 10V, f = 1MHz	-	700	-	pF
Output Capacitance	C _{oss}		-	120	-	
Reverse Transfer Capacitance	C _{rss}		-	105	-	
Switching Characteristics⁴						
Total Gate Charge	Q _g	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 5A	-	10.5	-	nC
Gate-Source Charge	Q _{gs}		-	2	-	
Gate-Drain Charge	Q _{gd}		-	2.5	-	
Turn-On Time	t _{d(on)}	V _{GS} = 5V, V _{DD} = 10V, I _D = 5A, R _G = 3Ω,	-	10	-	ns
Rise Time	t _r		-	20	-	
Turn-Off Time	t _{d(off)}		-	32	-	
Fall Time	t _f		-	12	-	
Source-Drain Diode Characteristics						
Body Diode Voltage ³	V _{SD}	I _S = 4A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	I _S		-	-	8	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



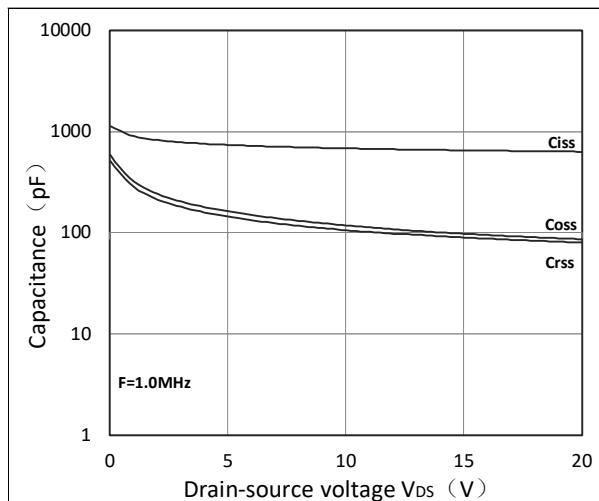


Figure 7. Capacitance Characteristics

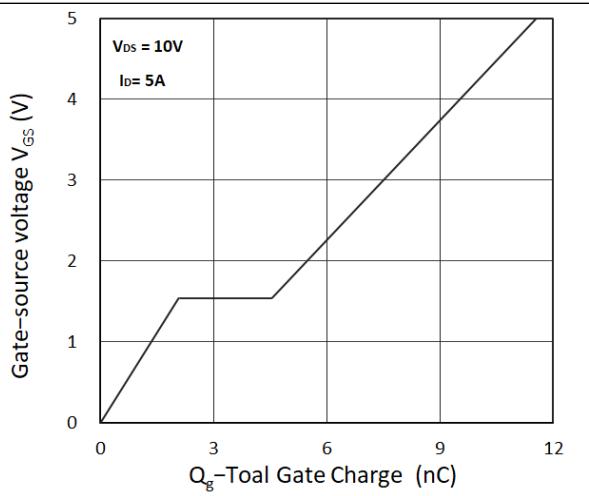
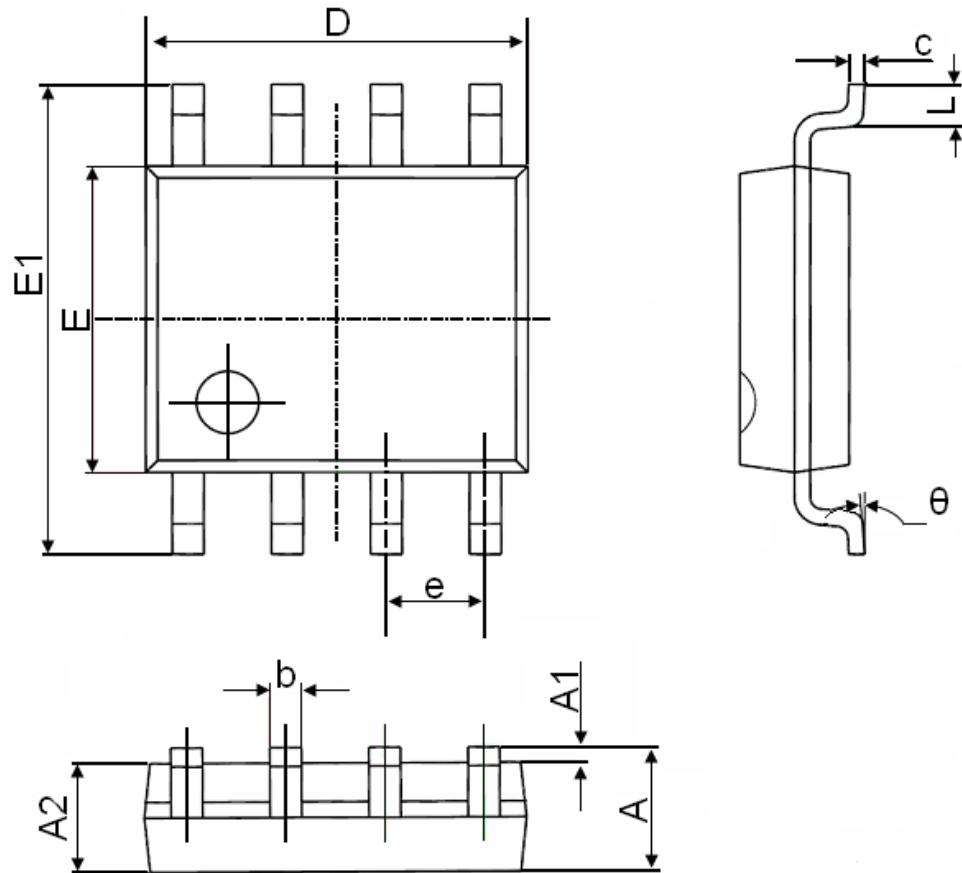


Figure 8. Gate Charge Characteristics

Package Mechanical Data-SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°